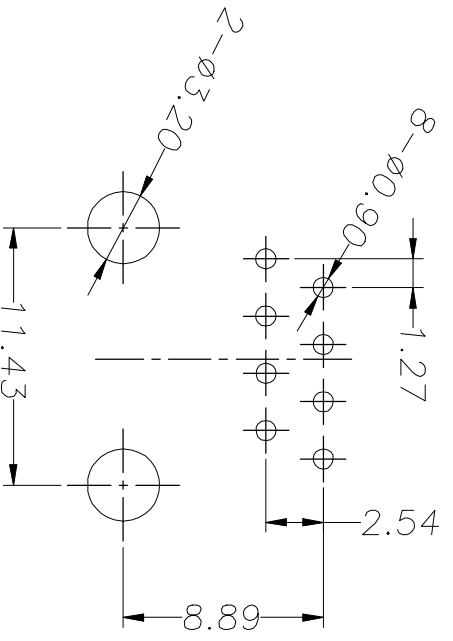
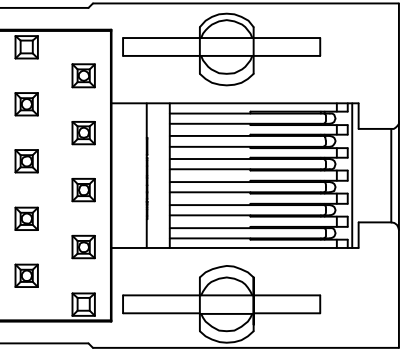
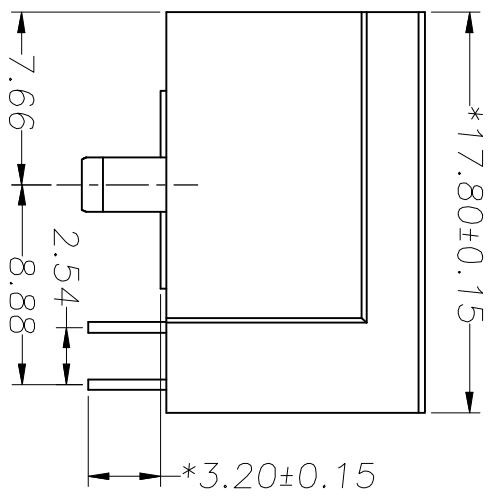
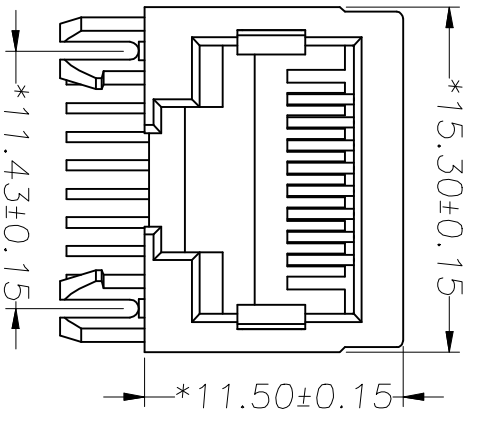


CATEGORY	DESCRIPTION	P/N #
CONNECTOR	Modular Jack, 10P8C, 1x1PORT	MJ562208-LX11-RN1

REV.	ECN NO	DESCRIPTION	REVISED	DATE
A01	---	New Release	Kelly	2008.07.13



PC Board Layout

NOTES:

MATERIAL:

1. HOUSING MATERIAL :GLASS FILLED POLYESTER(UL94V-0).
2. CONTACT MATERIAL :PHOSPHOR BRONZE Ø0.46mm (C5100).
3. PLATING :GOLD PLATING OVER NICKEL.
4. SHIELD. COPPER ALLOY 0.20mm THICKNESS PLATING NI.

ELECTRICAL:

1. VOLTAGE RATING :125 VAC RMS.
2. CURRENT RATING :1.5 AMP.
3. CONTACT RESISTANCE :50 MILLIOHMS MAX.
4. INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC.
5. DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

1. DURRABILITY :750 CYCLES MIN.
2. PCB RETENTION PRE-SOLDER :1 LB MIN.

ENVIRONMENTAL:

1. STORAGE :-40°C TO +85°C.
 2. OPERATION : 0°C TO 70°C.
- MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68,SUBPART F.

PART NUMBER:

Part No.: MJ562208-LX11-RN1

Table 1

	Material & Plating
X	Terminal Plating
0	Au 1u" Plating
1	Au 3u" Plating
2	Au 6u" Plating
3	Au 15u" Plating
4	Au 30u" Plating
5	Au 50u" Plating

Product Drawing
Dongguan Hejing Electronic Co.,LTD

UNLESS OTHERWISE SPECIFIED TOLERANCES	SCALE:1/1 UNIT: mm	DWG.NO:	WI-061-751
DECIMALS: X :±0.5	SIZE: A3	PAGE:1 OF 1	REV:A01
ANGLES: X :±2°	APPROVED BY	CHECKED BY	PREPARED BY
X.X :±0.3	Tony	Bill	Kelly
X.XX :±0.2	CUSTOMER COPY		